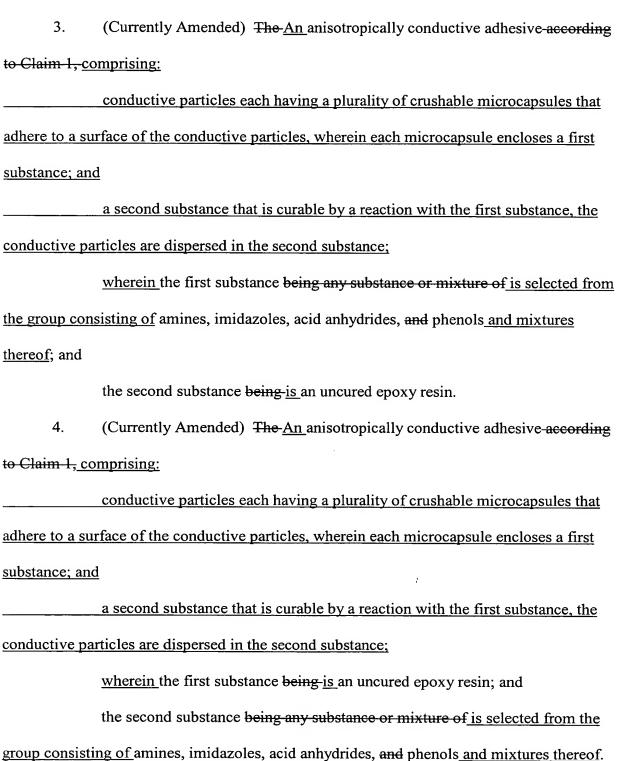
Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1.-2. (Canceled)



- 5. (Currently Amended) The anisotropically conductive adhesive according to Claim 1 Claim 3, capsule walls of the microcapsules comprising a thermoplastic resin.
 - 6. 17 (Canceled)
- 18. (Currently Amended) The anisotropically conductive adhesive according to Claim 1 Claim 3, wherein the second substance contains a third substance that is curable by a reaction with the second substance, the reaction occurring by heating

the third substance being any substance or mixture of is selected from the group consisting of imidazoles, acid anhydrides, and phenols and mixtures thereof.

19. (Currently Amended) The anisotropically conductive adhesive according to Claim 2 Claim 4, wherein the second substrate contains a third substance that is curable by a reaction with the second substance, the reaction occurring by heating,

the third substance being any substance or mixture of is selected from the group consisting of imidazoles, acid anhydrides, and phenols and mixtures thereof.